PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5940520

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
MD RASHIDUL ISLAM	01/22/2020
CHIYA SAEIDI	01/22/2020
YONG-HO LIM	01/22/2020
HUGH K. SMITH	01/22/2020
MARTIN RABINDRA PAIS	01/22/2020

RECEIVING PARTY DATA

Name:	MOTOROLA MOBILITY LLC
Street Address:	222 WEST MERCHANDISE MART PLAZA
Internal Address:	SUITE 1800
City:	CHICAGO
State/Country:	ILLINOIS
Postal Code:	60654

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16751777

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	DAVID A. MORASCH
SIGNATURE:	/ Dave Morasch 42905 /
DATE SIGNED:	01/31/2020

Total Attachments: 3

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ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, we, **MD Rashidul Islam, Glen Ellyn, IL**; **Chiya Saeidi, Chicago, IL**; **Yong-Ho Lim, Kildeer, IL**; **Hugh K. Smith, Palatine, IL**; and **Martin Rabindra Pais, North Barrington, IL**; have sold, assigned and transferred, and do hereby sell, assign and transfer, unto MOTOROLA MOBILITY LLC, a Limited Liability Company of the State of Delaware, having its principal office in Chicago, State of Illinois, United States of America, and its successors, assigns, and legal representatives, the entire right, title and interest for the United States of America in and to certain inventions described, illustrated and claimed in the following applications:

U.S. Application filed herein and entitled: **"Managing Antenna Module Heat and RF Emissions"**

I hereby also sell, assign and transfer unto Assignee, the entire right, title and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of the invention and the applications for Letters Patent in foreign countries, and I further authorize Assignee to apply for Letters Patent in foreign countries directly in its own name, and to claim priority of the filing date of the application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby also sell, assign and transfer unto Assignee, the entire right, title and interest in and to other applications for Letters Patent on the inventions referenced in this Assignment and Agreement, and all rights, title and interest in and to all applications for Letters Patent in respect of the invention filed under any and all international conventions and treaties together with the entire right, title and interest in and to Letters Patent which may be issued upon the application(s) or any application(s) otherwise claiming priority thereto, and upon any divisions, extensions, continuations, reissues and/or re-examinations of such application(s).

I further authorize Assignee to apply for Letters Patent directly in its own name where applicable, and to claim priority of the filing date of the application for Letters Patent filed under the laws of the applicable country and under the provisions of any and all international conventions and treaties.

I hereby authorize Assignee to request the Commissioner of Patents of the United States of America to issue any Letters Patents upon the aforesaid application, divisions, extensions, continuations, reissues or re-examinations, to Assignee, for the sole use and benefit of Assignee, to the full end of the term for which Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize Assignee to request the equivalent authorities in foreign countries to issue the patents of their respective countries to Assignee.

I agree that, when requested, I will, without charge to Assignee, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing, maintaining and enforcing patents for the inventions in any and all countries and for vesting title thereto in Assignee.

I covenant with Assignee that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

(1) Legal Name of Inventor: **MD Rashidul Islam**

Signature: Rashidul Date: 01.22.2020

(2) Legal Name of Inventor: **Chiya Saeidi**

Signature: C Saidi Date: 01-22-2020

(3) Legal Name of Inventor: **Yong-Ho Lim**

Signature: Date: 01 / 22 / 2020

(3) Legal Name of Inventor: **Hugh K. Smith**

Signature: Hugh K Smith Date: 1/22/2020

(4) Legal Name of Inventor: **Martin Rabindra Pais**

Signature: Martin Rabindra Pais Date: Jan 22, 2020